SPIRE-UCF-COM-001504

From: Matt Griffin [Matt.Griffin@astro.cf.ac.uk]

Sent: 15 January 2003 17:18

To: Astrid Heske

Cc: Ken King; Eric Sawyer; Bruce Swinyard; Judy Long

Subject: IBDR close-out





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Hello Astrid,

- * The attached WORD document gives the current status of the main actions/recommendations from the IBDR, based on the list you sent. Let us know if you have any comments or if you need any further elaboration at this stage.
- * We'll consider workable IHDR dates and get back to you on that in a couple of days. I propose that we have a discussion on the IHDR objectives and agenda at our next interface meeting in February.

Cheers,

Matt

SPIRE IBDR Close-Out Summary

Matt Griffin, Ken King, Eric Sawyer

14 January 2003

IBDR Board Recommendation (R)		Status
/A	Action (A) / Conclusion (C)	
R-01	Assess the impacts of the slow-down of the Project team activities, due to the funding situation, and propose priorities.	Prioritisation has been implemented with full visibility and consultation with ESA and industry. Thermal modelling effort in particular has been maintained. Priority has also been given to definition of the grounding scheme, 300-mK thermal strap programme, spacecraft interface definition, and vibration levels.
		EMC modelling, PA, microphonics, and some subsystem liaison have received less attention than we would like.
		Project Team effort overall is to be increased now that additional funding is to be made available from ESA.
R-02	Urgently consolidate the schedule; specifically clarify the planning of immature subsystems and clarify the AIV/AIT Plan accordingly.	Subsystem schedules have been closely monitored by Project Team, especially critical path subsystems (detectors and DRCU). The JPL programme has been modified to deliver detector arrays on time by restricting testing.
		The AIT plan has been defined in detail for the CQM, with two options identified - restricted testing/on-time delivery and full testing /later delivery. A decision on which to follow will be made in consultation with industry and will depend on industry readiness.
R-03	Make special efforts to advance the status of the DRCU and thermal bus bar to a level	The grounding scheme has been defined allowing long-lead PSU procurement to go ahead.
	equivalent with the rest of the instrument.	A warm electronics programme review is planned for March 2003 with the objective of establishing a model delivery schedule compatible with need dates, and preparing for the IHDR.
		The DCU EM has been manufactured and some tests already completed. It will be tested with representative bolometers in February 2003.
		The 300-mK thermal strap programme has been pursued as high priority. A design review was held in July and a Delta-review is planned for January. A substantial vibration and thermal test programme has continued and a viable design is now close to finalisation. The full system will be tested in the S TM in May.
R-04	Urgently renew efforts to freeze outstanding interface with the spacecraft, both thermal and	Thermal modelling has proceeded with industry with full availability and participation of the RAL thermal engineering group.
	straylight.	Difficult problems and compro mises remain necessary as a result of SPIRE being designed originally with respect to an invalid spacecraft thermal model. This issue continues to get high priority.
		The SPIRE stray light model has been provided to industry, and SPIRE has monitored and commented on the activities of the Herschel Optical Systems Working Group.

R-05	Plan PA activities appropriately	Reduced System FMECA has been submitted.
103	and allocate sufficient resources.	Reduced System I Wheel has been submitted.
	In particular, finalise the system	WCA on DRCU spacecraft interfaces will be included in DRCU review
	FMECA and derating WCA	in March
	analysis. Detailed manufacturing	
	flow charts featuring MIPs and	The AIV plan is being further detailed to include system-level MIPS and
	KIPs must be made available.	KIPS, and subsystems are being asked to provide their subsystem-level AIV plans with their MIPS and KIPS.
R-06	Improve configuration control,	The ECR database has been set up and works effectively. Not enough of
100	both at system and sub-system	the documentation is yet under formal configuration control.
	level.	
		Nearly all JPL documents are now under configuration control, and
		DRCU review will help - more project team effort will need to be
		devoted to this over the next six months.
		We regard our configuration control system as adequate (including the
		use of Livelink), but the actual work on documentation needs to be
		implemented.
		Project Team effort on this will be increased with the objective of
		establishing full configuration control on all relevant documents by the
		time of the IHDR.
		The CIDL maintenance is being reviewed and the system may be
		changed (but we do not regard this as a major issue).
R-07	Give special care to early testing	BDA vibration qualification is taking place now.
	of high-risk items, such as SMEC,	ON ATTOCAL CONTRACTOR OF THE C
	the BDAs and microphonics.	SMEC testing will await the STM.
		Meaningful system-level microphonics tests must await the CQM. In
		the meantime, unit level testing of the BDAs at JPL, and testing of the
		DCU with prototype arrays at Boulder and Saclay, will provide
		indicative data.
		In ganaral, consortium resources and the schedule are not competible
		In general, consortium resources and the schedule are not compatible with the level of prototyping and early testing that would be ideal.
R-08	Make available a software	The SW Validation and Verification Plan has been written and is
	development and verification plan.	available in draft form. It is now being reviewed prior to acceptance
		tests on the OBS which will take place in mid-February.
C-01	Address all recommendations and	Ongoing.
A 01	close out specific actions	Coa D. O1 above
A-01	Evaluate the impact of the reduced resources of the system team and	See R-01 above.
	define priorities .	
A-02	Agree with ESA Project and	See R-04 above.
	Industry on the thermal interfaces.	